

DOCKET NO. 01-C-084 (STMI01-01084)

PATENT

Customer No. 30425



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : Harry Michael Siegel, et al.

Serial No. : 10/066,245

Filed : January 31, 2002

For : METHOD FOR USING A PRE-FORMED FILM IN A TRANSFER
MOLDING PROCESS FOR AN INTEGRATED CIRCUIT (AS
AMENDED)

Group No. : 1791

Examiner : Edmund H. Lee

Confirmation No. : 2782

MAIL STOP AF

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

PRE-APPEAL REQUEST FOR REVIEW

The Applicants request review of the final rejection in the above-identified application. No amendments are being filed with this request. This request is being filed with a notice of appeal. This review is requested for the reasons stated in the arguments below, demonstrating the clear legal and factual deficiency of the rejections of some or all of the claims.

The final rejection rejects the claims solely under the written description requirement of 35 U.S.C. § 112, first paragraph, stating:

Suspension of the film below the mold cavity surface of the transfer mold (cl

1, ln 9; cl 7, ln 10; cl 12, ln 10 and 19) lacks support in the instant disclosure. The

transfer mold 100 against the lower surface 140 of the top half of transfer mold 100. However, contrary to the assertion within the final rejection, the specification describes use of a vacuum to hold the pre-formed film 600 in place against the surface of transfer mold 100 as the transfer mold 100 is placed over the integrated circuit die 180 and substrate 190:

The first step of the method is to provide a film 600 of compliant material (step 910). Then film 600 is pre-formed to conform the shape of film 600 to the surface of the mold cavity of transfer mold 100 (step 920). Then pre-formed film 600 is placed within the mold cavity of transfer mold 100 (step 930). As previously described, pre-formed film 600 may be held in place within the mold cavity of transfer mold 100 by applying a vacuum to channels 120, 122, 160, 162, 164 and 166 of transfer mold 100.

Then transfer mold 100 is placed on top of integrated circuit die 180 and substrate 190 (step 940). Pre-formed film 600 then covers the surfaces of integrated circuit die 180 and substrate 190.

Specification, page 20, lines 13-20. When held by a vacuum against the surface of transfer mold 100 as the transfer mold 100 is placed on top of integrated circuit die 180 and substrate 190 (as depicted in Figure 6), the pre-formed film 600 will inherently be suspended below the transfer mold 100.


As a result of the foregoing, the Applicant asserts that the claims in the Application are in condition for allowance over all art of record, and that the rejections are both factually and legally deficient, and respectfully requests this case be returned to the Examiner for allowance or, alternatively, further examination.

ATTORNEY DOCKET NO. 01-C-084 (STMI01-01084)
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Respectfully submitted,

MUNCK CARTER, P.C.

Date: 12-19-2008



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